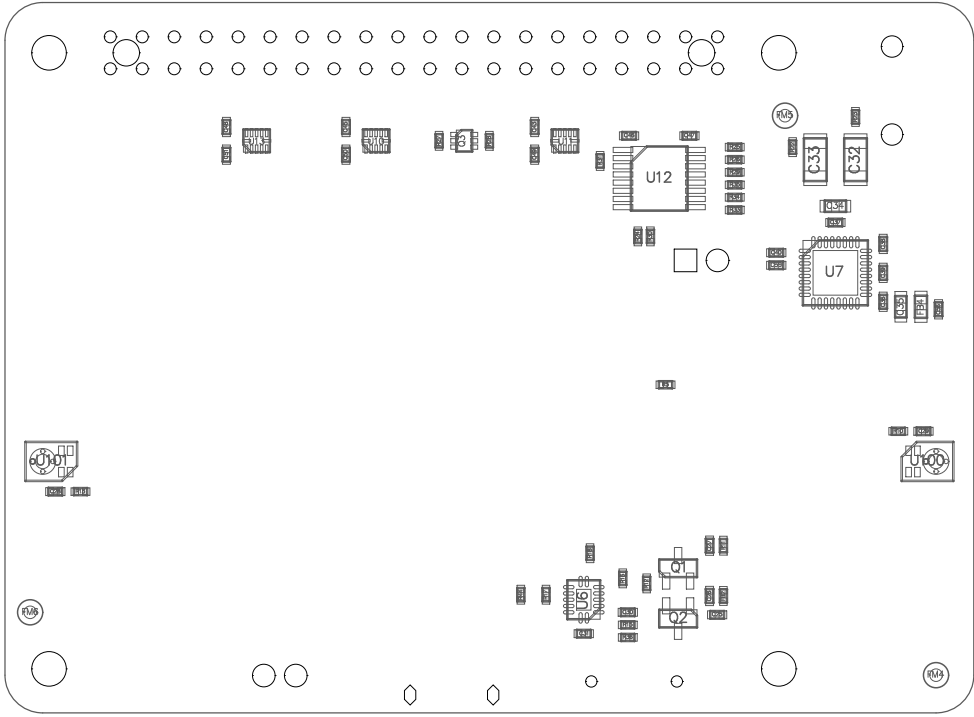


PCB ASSEMBLY INSTRUCTIONS

- 1.) SOLDERPASTE – ROHS/LEAD FREE NO CLEAN SOLDERPASTE.
PADS HAVE NOT BEEN UNDERSIZED.
ASSEMBLER SHOULD UNDERSIZE PADS TO SUIT PROCESS.
SUGGEST 125UM MAX STENCIL THICKNESS.
- 2.) ENSURE THROUGH HOLE PINS OF USB CONNECTOR J5 ARE SOLDERED IN ADDITION TO SMD PADS.
- 3.) TWO PIN COMPONENT ORIENTATION:
POLARISED MOLDED CAPACITORS – PIN 1 IS THE POLARITY MARK PIN (POSITIVE).
MOLDED DIODES – PIN 1 IS THE POLARITY MARK PIN (CATHODE).
- 4.) NOTE USB CONNECTOR J5 HAS A LIP THAT SITS BELOW PCB SURFACE.
PANELISATION SHOULD ENSURE CLEARANCE FOR THIS TO ALLOW THE CONNECTOR TO SIT FLAT.
- 5.) COMPONENTS U100 AND U101 HAVE A PORT HOLE OPENING WHICH IS VERY SENSITIVE TO CONTAMINATION.
EXAMPLE CONTAMINATION COULD BE BY SOLDER FLUX, CLEANING SOLVENTS, SAWING DUST OR OTHER FOREIGN MATERIAL.
CARE SHOULD BE TAKEN TO MINIMISE THE LIKELIHOOD OF CONTAMINATION.
PROTECTIVE TAPE SHOULD BE APPLIED OVER THE PORT HOLE OPENING IMMEDIATELY FOLLOWING REFLOW TO PROTECT AGAINST SUBSEQUENT CONTAMINATION.
- 6.) WAVE SOLDERING SHALL NOT BE USED.
- 7.) VAPOR PHASE REFLOW SHALL NOT BE USED.
- 8.) DO NOT EMPLOY CHEMICAL BOARD WASH OR CLEANING.
- 9.) DO NOT USE HIGH PRESSURE AIR NEAR THE BOARD.

XMS0001 = 1V0 = 23 AUG 2021
TOP ASSEMBLY



BOTTOM ASSEMBLY